Icemos Technology Ltd Product Specification 1000.681901 Issue Date 15 March 2021 09:25:

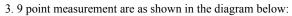
D M 1	O 4	
Part Number	Customer	

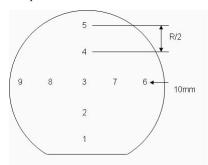
Category		Parameter	Specification	Measurement Method
OverallWafer	1.0	Diameter	150.00 +/- 0.30 mm	
	2.0	Primary Flat Orientation	<110> +/- 1 degree	Wafer Vendor
	3.0	Primary Flat Length	57.50 +/- 2.50 mm	Wafer Vendor
	4.0	Secondary Flat Orientation	semi std/none	
	5.0	Overall Thickness	643.00 +/- 11.00 μm	ADE 100%
	6.0	Total Thickness Variation (TTV)	<3.00μm	Guaranteed by Process
	7.0	Bow	<60.00μm	ADE to ASTM F534, 20% Best effort not guaranteed
	8.0	Warp	<60.00μm	ADE to ASTM F657, 20% Best effort not guaranteed
	9.0	Edge Chips	0	Bright Light, 100% (note 2)
	10.0	Edge Exclusion	5mm	
HandleSilicon	11.0	Handle Growth Method	CZ	Wafer Vendor
	12.0	Handle Orientation	{100} +/- 1 degree	Wafer Vendor
	13.0	Handle Thickness	600.00 +/- 10.00 μm	ADE, 100%
	14.0	Handle Doping Type	N	Wafer Vendor
	15.0	Handle Dopant	Any	Wafer Vendor
	16.0	Handle Resistivity	0.002 - 0.01 Ohmem	Wafer Vendor
	17.0	Backside Finish	Polished with laser mark and oxide.	Guaranteed by process
BuriedOxide	18.0	Oxide Type	Thermal	
	19.0	Oxide Thickness	30,000.00 +/- 3,000.00 A	Nanospec centre point, 4%
DeviceSilicon	20.0	Device Growth Method	CZ	Wafer Vendor
	21.0	Device Orientation	{100} +/- 1 degree	Wafer Vendor
	22.0	Nominal Thickness	40.00 +/- 0.50 μm	Filmetrics 9 point, 100%
	23.0	Device Doping Type	N	Wafer Vendor
	24.0	Device Dopant	Any	Wafer Vendor
	25.0	Device Resistivity	0.002 - 0.01 Ohmem	Wafer Vendor
	26.0	Distance to device silicon edge from wafer edge	< 2mm from outermost wafer edge	Guaranteed by process
	27.0	Edge Removal Depth in Handle	<100um	Guaranteed by process
	28.0	Voids	0	Bright Light, 100% (note 2)
	29.0	Scratches	0	Bright Light, 100% (note 2)
	30.0	Haze	none	Bright Light, 100% (note 2)

Page 1 of 2 19/07/2021 www.icemostech.com

Part Number		Customer		
Category	Parameter	Specification	Measurement Method	
Shipping Details	Wafer per box :	Max 25		
	Packaging:	Taped Polypropylene Wafer Box Empak, Ultrapak, 150.00mm Antistatic Double Bagging		
	Lot Shipment Data	Device Thickness Bow / Warp Data Handle and SOI Thickness		
Explanatory Notes	1. Microscope inspec	ction performed using microscope scan as below. 5x objective.		
	2. All bright light inspections performed exclude all wafer area outside the edge exclusion defined in Overall			

Wafer, Edge Exclusion. High intensity bright lamp inspection as per ASTM F523.





Additional Information